

Integrated Device Technology, Inc.

## FAST CMOS OCTAL LATCHED TRANSCEIVER

IDT54/74FCT543  
IDT54/74FCT543A  
IDT54/74FCT543C

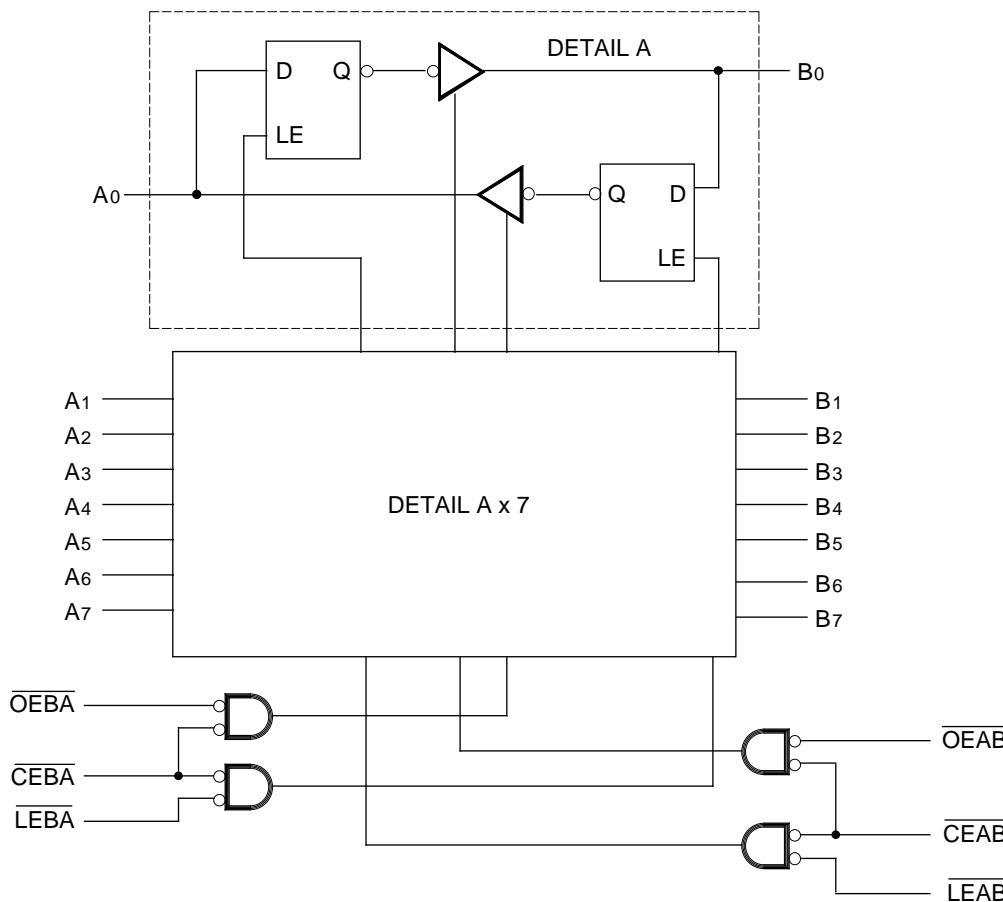
### FEATURES:

- IDT54/74FCT543 equivalent to FAST™ speed
- **IDT54/74FCT543A 25% faster than FAST**
- **IDT54/74FCT543C 40% faster than FAST**
- Equivalent to FAST output drive over full temperature and voltage supply extremes
- $I_{OL} = 64\text{mA}$  (commercial),  $48\text{mA}$  (military)
- Separate controls for data flow in each direction
- Back-to-back latches for storage
- CMOS power levels ( $1\text{mW}$  typ. static)
- Substantially lower input current levels than FAST ( $5\mu\text{A}$  max.)
- TTL input and output level compatible
- CMOS output level compatible
- Product available in Radiation Tolerant and Radiation Enhanced versions
- Military product compliant to MIL-STD-883, Class B

### DESCRIPTION:

The IDT54/74FCT543/A/C is a non-inverting octal transceiver built using an advanced dual metal CMOS technology. These devices contain two sets of eight D-type latches with separate input and output controls for each set. For data flow from A to B, for example, the A-to-B Enable (CEAB) input must be LOW in order to enter data from  $A_0-A_7$  or to take data from  $B_0-B_7$ , as indicated in the Function Table. With  $\overline{\text{CEAB}}$  LOW, a LOW signal on the A-to-B Latch Enable (LEAB) input makes the A-to-B latches transparent; a subsequent LOW-to-HIGH transition of the LEAB signal puts the A latches in the storage mode and their outputs no longer change with the A inputs. With  $\overline{\text{CEAB}}$  and  $\overline{\text{OEAB}}$  both LOW, the 3-state B output buffers are active and reflect the data present at the output of the A latches. Control of data from B to A is similar, but uses the  $\overline{\text{CEBA}}$ ,  $\overline{\text{LEBA}}$  and  $\overline{\text{OEBA}}$  inputs.

### FUNCTIONAL BLOCK DIAGRAMS



2614 drw 01

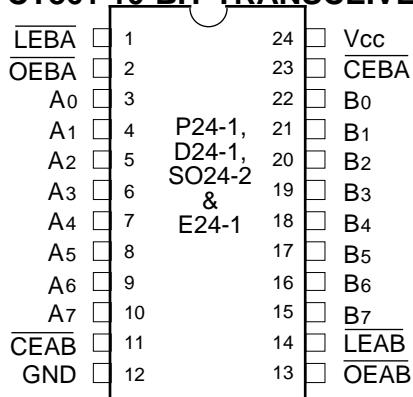
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MILITARY AND COMMERCIAL TEMPERATURE RANGES

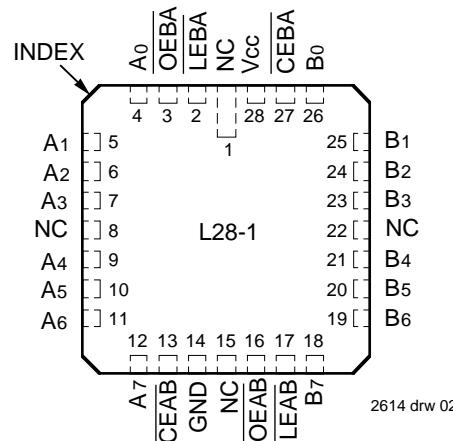
MAY 1992

## PIN CONFIGURATIONS

### IDT54/74FCT861 10-BIT TRANSCEIVERS



DIP/SOIC/CERPACK  
TOP VIEW



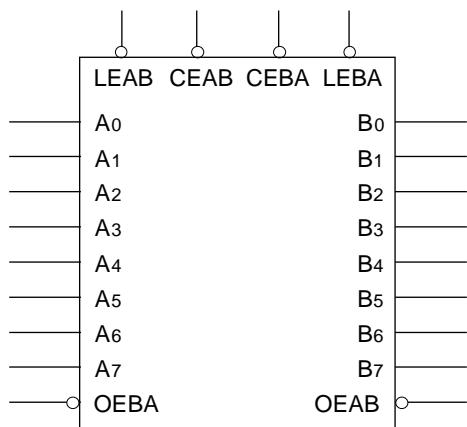
LCC  
TOP VIEW

## PIN DESCRIPTION

Pin Names	Description
OEAB	A-to-B Output Enable Input (Active LOW)
OEBA	B-to-A Output Enable Input (Active LOW)
CEAB	A-to-B Enable Input (Active LOW)
CEBA	B-to-A Enable Input (Active LOW)
LEAB	A-to-B Latch Enable Input (Active LOW)
LEBA	B-to-A Latch Enable Input (Active LOW)
A <sub>0</sub> -A <sub>7</sub>	A-to-B Data Inputs or B-to-A 3-State Outputs
B <sub>0</sub> -B <sub>7</sub>	B-to-A Data Inputs or A-to-B 3-State Outputs

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## LOGIC SYMBOL



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## FUNCTION TABLE (1,2)

For A-to-B (Symmetric with B-to-A)

Inputs			Latch Status	Output Buffers
CEAB	LEAB	OEAB	A-to-B	B <sub>0</sub> -B <sub>7</sub>
H	—	—	Storing	High Z
—	H	—	Storing	—
—	—	H	—	High Z
L	L	L	Transparent	Current A Inputs
L	H	L	Storing	Previous* A Inputs

NOTES:

1. \* Before LEAB LOW-to-HIGH Transition

H = HIGH Voltage Level

L = LOW Voltage Level

— = Don't Care or Irrelevant

2. A-to-B data flow shown; B-to-A flow control is the same, except using CEBA, LEBA and OEBA.

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## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Rating	Commercial	Military	Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
VTERM <sup>(3)</sup>	Terminal Voltage with Respect to GND	-0.5 to Vcc	-0.5 to Vcc	V
TA	Operating Temperature	0 to +70	-55 to +125	°C
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
TSTG	Storage Temperature	-55 to +125	-65 to +150	°C
PT	Power Dissipation	0.5	0.5	W
IOUT	DC Output Current	120	120	mA

### NOTES:

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- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability. No terminal voltage may exceed Vcc by +0.5V unless otherwise noted.
- Inputs and Vcc terminals only.
- Outputs and I/O terminals only.

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- This parameter is guaranteed by characterization data and not tested.

## CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	6	10	pF
Cl/O	I/O Capacitance	VOUT = 0V	8	12	pF

## DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: VLC = 0.2V, VHC = Vcc - 0.2V

Commercial: TA = 0°C to +70°C, Vcc = 5.0V ± 5%; Military: TA = -55°C to +125°C, Vcc = 5.0V ± 10%

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Typ. <sup>(2)</sup>	Max.	Unit
VIH	Input HIGH Level	Guaranteed Logic HIGH Level		2.0	—	—	V
VIL	Input LOW Level	Guaranteed Logic LOW Level		—	—	0.8	V
IIH	Input HIGH Current (Except I/O pins)	Vcc = Max.	VI = Vcc	—	—	5	µA
IIH	Input HIGH Current (I/O pins Only)		VI = 2.7V	—	—	5 <sup>(4)</sup>	
IIL	Input LOW Current (Except I/O pins)		VI = 0.5V	—	—	-5 <sup>(4)</sup>	µA
IIL	Input LOW Current (I/O pins Only)		VI = GND	—	—	-5	
IIH	Input HIGH Current (I/O pins Only)	Vcc = Max.	VI = Vcc	—	—	15	µA
IIL	Input LOW Current (I/O pins Only)		VI = 2.7V	—	—	15 <sup>(4)</sup>	
VIK	Clamp Diode Voltage	Vcc = Min., IN = -18mA		—	-0.7	-1.2	V
Ios	Short Circuit Current	Vcc = Max. <sup>(3)</sup> , VO = GND		-60	-120	—	mA
VOH	Output HIGH Voltage	Vcc = 3V, VIN = VLC or VHC, IOH = -32µA Vcc = Min. VIN = VIH or VIL	VHC	Vcc	—	—	V
VOH	Output HIGH Voltage		IOH = -300µA	VHC <sup>(4)</sup>	VCC	—	
VOH	Output HIGH Voltage		IOH = -12mA MIL.	2.4	4.3	—	
VOH	Output HIGH Voltage		IOH = -15mA COM'L.	2.4	4.3	—	
VOL	Output LOW Voltage	Vcc = 3V, VIN = VLC or VHC, IOL = 300µA Vcc = Min. VIN = VIH or VIL	Vcc = 3V, VIN = VLC or VHC, IOL = 300µA	—	GND	VLC	V
VOL	Output LOW Voltage		IOL = 300µA	—	GND	VLC <sup>(4)</sup>	
VOL	Output LOW Voltage		IOL = 48mA MIL. <sup>(5)</sup>	—	0.3	0.55	
VOL	Output LOW Voltage		IOL = 64mA COM'L. <sup>(5)</sup>	—	0.3	0.55	

### NOTES:

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- For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at Vcc = 5.0V, +25°C ambient and maximum loading.
- Not more than one output should be shorted at one time. Duration of the short circuit test should not exceed one second.
- This parameter is guaranteed but not tested.
- These are maximum IOL values per output, for 8 outputs turned on simultaneously. Total maximum IOL (all outputs) is 512mA for commercial and 384mA for military. Derate IOL for number of outputs exceeding 8 turned on simultaneously.

POWER SUPPLY CHARACTERISTICS  $V_{LC} = 0.2V$ ;  $V_{HC} = V_{CC} - 0.2V$ 

Symbol	Parameter	Test Conditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Unit	
$I_{CC}$	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$ $V_{IN} \geq V_{HC}; V_{IN} \leq V_{LC}$	—	0.2	1.5	mA	
$\Delta I_{CC}$	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = \text{Max.}, V_{IN} = 3.4V$ <sup>(3)</sup>	—	0.5	2.0	mA	
$I_{CCD}$	Dynamic Power Supply Current <sup>(4)</sup>	$V_{CC} = \text{Max.}, \text{Outputs Open}$ $\overline{CEAB}$ and $\overline{OEAB} = GND$ $CEBA = V_{CC}$ One Input Toggling 50% Duty Cycle	$V_{IN} \geq V_{HC}$ $V_{IN} \leq V_{LC}$	—	0.15	0.25	mA/ MHz
$I_C$	Total Power Supply Current <sup>(6)</sup>	$V_{CC} = \text{Max.}, \text{Outputs Open}$ $f_{CP} = 10MHz$ (LEAB) 50% Duty Cycle $CEAB$ and $\overline{OEAB} = GND$ $CEBA = V_{CC}$ One Bit Toggling at $f_i = 5MHz$ 50% Duty Cycle	$V_{IN} \geq V_{HC}$ $V_{IN} \leq V_{LC}$ (FCT)	—	1.7	4.0	mA
		$V_{IN} = 3.4V$ $V_{IN} = GND$	—	2.2	6.0		
		$V_{IN} \geq V_{HC}$ $V_{IN} \leq V_{LC}$ (FCT)	—	7.0	12.8 <sup>(5)</sup>		
		$V_{IN} = 3.4V$ $V_{IN} = GND$	—	9.2	21.8 <sup>(5)</sup>		

## NOTES:

- For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at  $V_{CC} = 5.0V$ ,  $+25^\circ C$  ambient.
- Per TTL driven input ( $V_{IN} = 3.4V$ ); all other inputs at  $V_{CC}$  or  $GND$ .
- This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- Values for these conditions are examples of the  $I_{CC}$  formula. These limits are guaranteed but not tested.

$$I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$$

$$I_C = I_{CC} + \Delta I_{CC} D_{HNT} + I_{CCD}(f_{CP}/2 + f_i N_i)$$

$I_{CC}$  = Quiescent Current

$\Delta I_{CC}$  = Power Supply Current for a TTL High Input ( $V_{IN} = 3.4V$ )

$D_H$  = Duty Cycle for TTL Inputs High

$N_T$  = Number of TTL Inputs at  $D_H$

$I_{CCD}$  = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

$f_{CP}$  = Clock Frequency for Register Devices (Zero for Non-Register Devices)

$f_i$  = Input Frequency

$N_i$  = Number of Inputs at  $f_i$

All currents are in millamps and all frequencies are in megahertz.

2614 tbl 06

## SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter	Condition <sup>(1)</sup>	IDT54/74FCT543				IDT54/74FCT543A				IDT54/74FCT543C				Unit	
			Com'l.		Mil.		Com'l.		Mil.		Com'l.		Mil.			
			Min. <sup>(2)</sup>	Max.												
tPLH tPHL	Propagation Delay Transparent Mode An to Bn or Bn to An	CL = 50pF RL = 500Ω	2.5	8.5	2.5	10.0	2.5	6.5	2.5	7.5	2.5	5.3	2.5	6.1	ns	
tPLH tPHL	Propagation Delay LEBA to An, LEAB to Bn		2.5	12.5	2.5	14.0	2.5	8.0	2.5	9.0	2.5	7.0	2.5	8.0	ns	
tpZH tpZL	Output Enable Time OEBA or OEAB to An or Bn CEBA or CEAB to An or Bn		2.0	12.0	2.0	14.0	2.0	9.0	2.0	10.0	2.0	8.0	2.0	9.0	ns	
tPHZ tPLZ	Output Disable Time OEBA or OEAB to An or Bn CEBA or CEAB to An or Bn		2.0	9.0	2.0	13.0	2.0	7.5	2.0	8.5	2.0	6.5	2.0	7.5	ns	
tsu	Set-up Time, HIGH or LOW An or Bn to LEBA or LEAB		3.0	—	3.0	—	2.0	—	2.0	—	2.0	—	2.0	—	ns	
tH	Hold Time, HIGH or LOW An or Bn to LEBA or LEAB		2.0	—	2.0	—	2.0	—	2.0	—	2.0	—	2.0	—	ns	
tw	LEBA or LEAB Pulse Width LOW		5.0	—	5.0	—	5.0	—	5.0	—	5.0	—	5.0	—	ns	

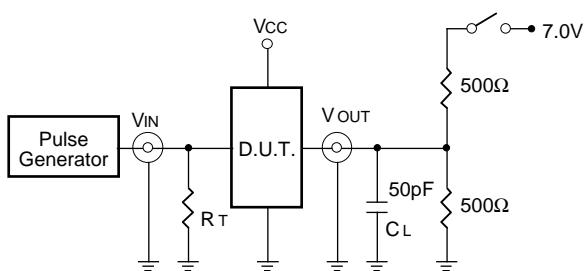
NOTES:

- See test circuits and waveforms.
- Minimum limits are guaranteed but not tested on Propagation Delays.

2513 tbl 07

## TEST CIRCUITS AND WAVEFORMS

### TEST CIRCUITS FOR ALL OUTPUTS



### SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

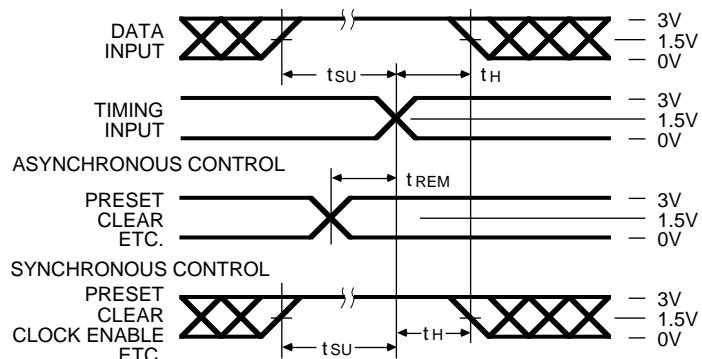
#### DEFINITIONS:

2614 tbl 08

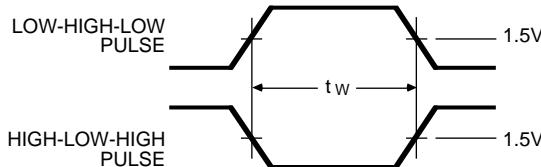
$CL$  = Load capacitance: includes jig and probe capacitance.

$RT$  = Termination resistance: should be equal to  $Z_{out}$  of the Pulse Generator.

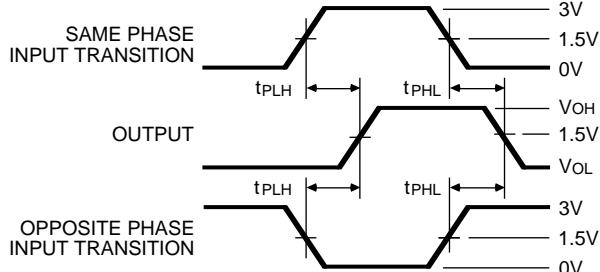
### SET-UP, HOLD AND RELEASE TIMES



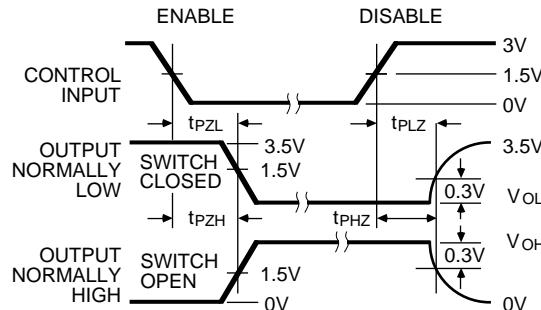
### PULSE WIDTH



### PROPAGATION DELAY



### ENABLE AND DISABLE TIMES

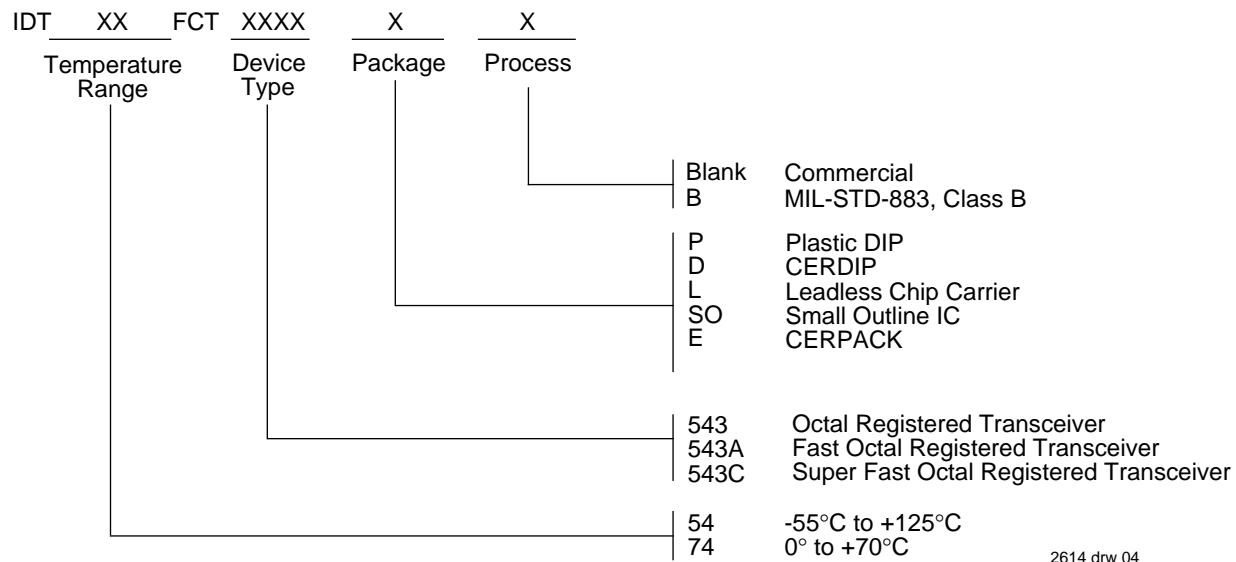


#### NOTES

2614 drw 05

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
2. Pulse Generator for All Pulses: Rate  $\leq 1.0$  MHz;  $Z_0 \leq 50\Omega$ ;  $t_f \leq 2.5$  ns;  $t_r \leq 2.5$  ns.

## ORDERING INFORMATION



2614 drw 04